4. Functional diagram

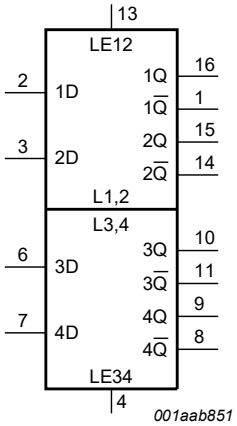


Fig. 1. Logic symbol

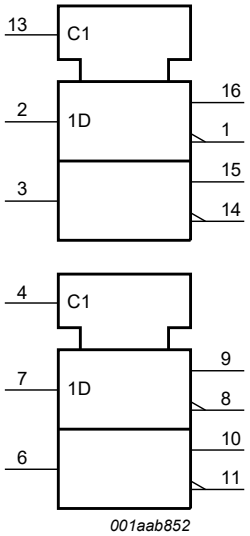


Fig. 2. IEC logic symbol

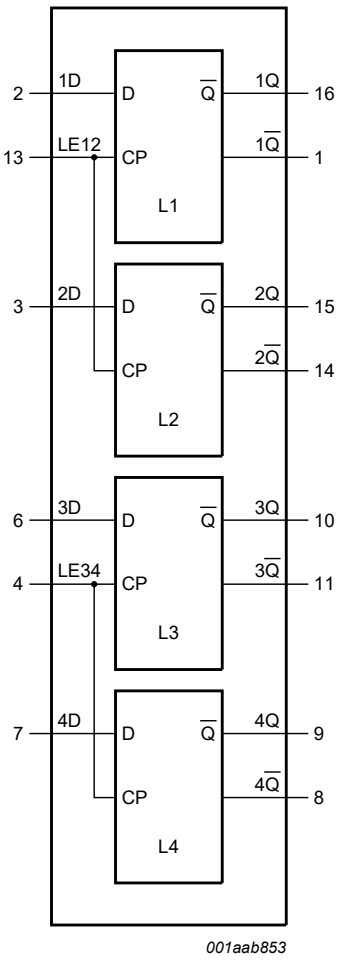


Fig. 3. Functional diagram

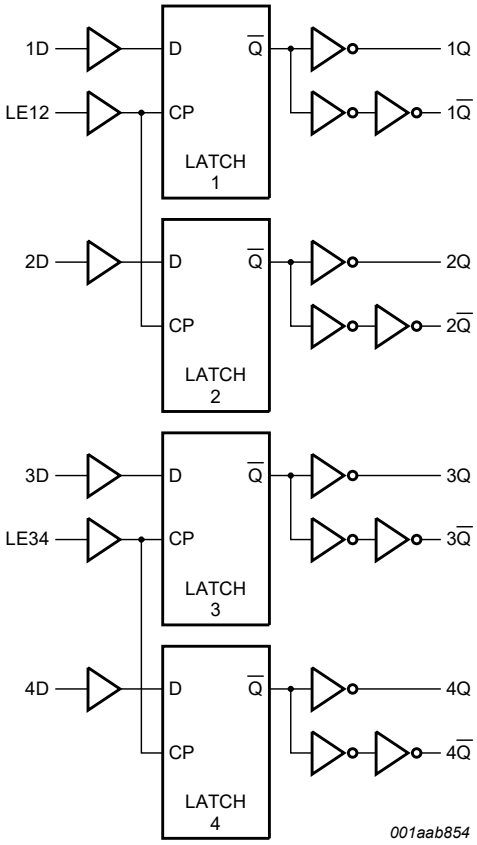


Fig. 4. Logic diagram

5. Pinning information

5.1. Pinning

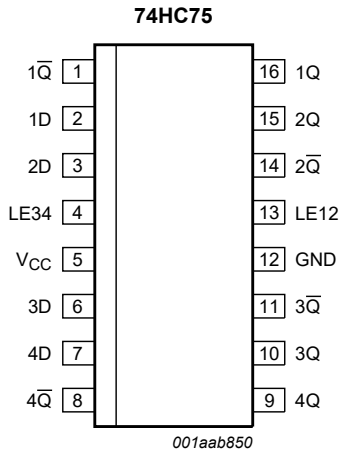


Fig. 5. Pin configuration SOT109-1 (SO16)

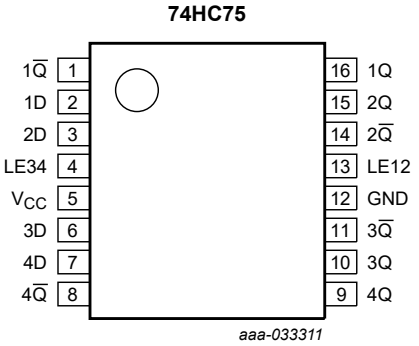


Fig. 6. Pin configuration SOT403-1 (TSSOP16)

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
1Q, 2Q, 3Q, 4Q	1, 14, 11, 8	complementary latch output
1D, 2D, 3D, 4D	2, 3, 6, 7	data input
LE34	4	latch enable input for latches 3 and 4 (active HIGH)
V_{CC}	5	positive supply voltage
GND	12	ground (0 V)
LE12	13	latch enable input for latches 1 and 2 (active HIGH)
1Q, 2Q, 3Q, 4Q	16, 15, 10, 9	latch output

6. Function description

Table 3. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care;
q = lower case letters indicate the state of the referenced output one set-up time prior to the HIGH-to-LOW LEnn transition.

Operating mode	Input		Output	
	LEnn	nD	nQ	nQ
Data enabled	H	L	L	H
	H	H	H	L
Data latched	L	X	q	q

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			-0.5	+7.0	V
I_{IK}	input clamping current	V_I < -0.5 V or V_I > V_{CC} + 0.5 V	[1]	-	±20	mA
I_{OK}	output clamping current	V_O < -0.5 V or V_O > V_{CC} + 0.5 V	[1]	-	±20	mA
I_O	output current	V_O = -0.5 V to V_{CC} + 0.5 V		-	±25	mA
I_{CC}	supply current			-	50	mA
I_{GND}	ground current			-50	-	mA
T_{stg}	storage temperature			-65	+150	°C
P_{tot}	total power dissipation	T_{amb} = -40 °C to +125 °C	[2]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
[2] For SOT109-1 (SO16) package: P_{tot} derates linearly with 12.4 mW/K above 110 °C.
For SOT403-1 (TSSOP16) package: P_{tot} derates linearly with 8.5 mW/K above 91 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		2.0	5.0	6.0	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V_{CC} = 2.0 V	-	-	625	ns/V
		V_{CC} = 4.5 V	-	1.67	139	ns/V
		V_{CC} = 6.0 V	-	-	83	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	1.2	-	V
		V_{CC} = 4.5 V	3.15	2.4	-	V
		V_{CC} = 6.0 V	4.2	3.2	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	0.8	0.5	V
		V_{CC} = 4.5 V	-	2.1	1.35	V
		V_{CC} = 6.0 V	-	2.8	1.8	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = -20 µA; V_{CC} = 2.0 V	1.9	2.0	-	V
		I_O = -20 µA; V_{CC} = 4.5 V	4.4	4.5	-	V
		I_O = -20 µA; V_{CC} = 6.0 V	5.9	6.0	-	V
		I_O = -4 mA; V_{CC} = 4.5 V	3.98	4.32	-	V
		I_O = -5.2 mA; V_{CC} = 6.0 V	5.48	5.81	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = 20 µA; V_{CC} = 2.0 V	-	0	0.1	V
		I_O = 20 µA; V_{CC} = 4.5 V	-	0	0.1	V
		I_O = 20 µA; V_{CC} = 6.0 V	-	0	0.1	V
		I_O = 4 mA; V_{CC} = 4.5 V	-	0.15	0.26	V
		I_O = 5.2 mA; V_{CC} = 6.0 V	-	0.16	0.26	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 6.0 V	-	-	±0.1	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	8.0	µA
C_I	input capacitance		-	3.5	-	pF
T_{amb} = -40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	V
		V_{CC} = 4.5 V	3.15	-	-	V
		V_{CC} = 6.0 V	4.2	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	V
		V_{CC} = 4.5 V	-	-	1.35	V
		V_{CC} = 6.0 V	-	-	1.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = -20 µA; V_{CC} = 2.0 V	1.9	-	-	V
		I_O = -20 µA; V_{CC} = 4.5 V	4.4	-	-	V
		I_O = -20 µA; V_{CC} = 6.0 V	5.9	-	-	V
		I_O = -4 mA; V_{CC} = 4.5 V	3.84	-	-	V
		I_O = -5.2 mA; V_{CC} = 6.0 V	5.34	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = 20 µA; V_{CC} = 2.0 V	-	-	0.1	V
		I_O = 20 µA; V_{CC} = 4.5 V	-	-	0.1	V
		I_O = 20 µA; V_{CC} = 6.0 V	-	-	0.1	V
		I_O = 4 mA; V_{CC} = 4.5 V	-	-	0.33	V
		I_O = 5.2 mA; V_{CC} = 6.0 V	-	-	0.33	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 6.0 V	-	-	±1.0	µA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	80	µA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	-	-	V
		V_{CC} = 4.5 V	3.15	-	-	V
		V_{CC} = 6.0 V	4.2	-	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	-	0.5	V
		V_{CC} = 4.5 V	-	-	1.35	V
		V_{CC} = 6.0 V	-	-	1.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}		-		
		I_O = -20 µA; V_{CC} = 2.0 V	1.9	-	-	V
		I_O = -20 µA; V_{CC} = 4.5 V	4.4	-	-	V
		I_O = -20 µA; V_{CC} = 6.0 V	5.9	-	-	V
		I_O = -4 mA; V_{CC} = 4.5 V	3.7	-	-	V
		I_O = -5.2 mA; V_{CC} = 6.0 V	5.2	-	-	V
V_{OL}	LOW-level output voltage	V_I = V_{IH} or V_{IL}		-		
		I_O = 20 µA; V_{CC} = 2.0 V	-	-	0.1	V
		I_O = 20 µA; V_{CC} = 4.5 V	-	-	0.1	V
		I_O = 20 µA; V_{CC} = 6.0 V	-	-	0.1	V
		I_O = 4 mA; V_{CC} = 4.5 V	-	-	0.4	V
		I_O = 5.2 mA; V_{CC} = 6.0 V	-	-	0.4	V
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 6.0 V	-	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	160	µA

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; $t_r = t_f$ = 6 ns; C_L = 50 pF; unless otherwise specified, for test circuit see Fig. 11.

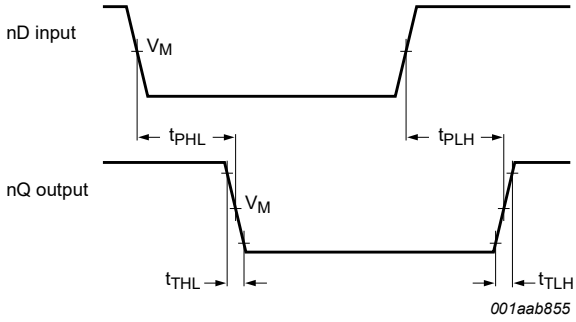
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
t_{pd}	propagation delay	nD to nQ; see Fig. 7 [1]				
		V_{CC} = 2.0 V	-	33	110	ns
		V_{CC} = 4.5 V	-	12	22	ns
		V_{CC} = 6.0 V	-	10	19	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	11	-	ns
		nD to $n\overline{Q}$; see Fig. 8 [1]				
		V_{CC} = 2.0 V	-	39	120	ns
		V_{CC} = 4.5 V	-	14	24	ns
		V_{CC} = 6.0 V	-	11	20	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	11	-	ns
		LEnn to nQ; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	33	120	ns
		V_{CC} = 4.5 V	-	12	24	ns
		V_{CC} = 6.0 V	-	10	20	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	11	-	ns
		LEnn to $n\overline{Q}$; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	39	125	ns
		V_{CC} = 4.5 V	-	14	25	ns
		V_{CC} = 6.0 V	-	11	21	ns
		V_{CC} = 5.0 V; C_L = 15 pF	-	11	-	ns
t_t	transition time	nQ, $n\overline{Q}$; see Fig. 7 and Fig. 8 [2]				
		V_{CC} = 2.0 V	-	19	75	ns
		V_{CC} = 4.5 V	-	7	15	ns
		V_{CC} = 6.0 V	-	6	13	ns
t_W	pulse width	LEnn HIGH; see Fig. 10				
		V_{CC} = 2.0 V	80	17	-	ns
		V_{CC} = 4.5 V	16	6	-	ns
		V_{CC} = 6.0 V	14	5	-	ns
t_{su}	set-up time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	60	14	-	ns
		V_{CC} = 4.5 V	12	5	-	ns
		V_{CC} = 6.0 V	10	4	-	ns
t_h	hold time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	3	-8	-	ns
		V_{CC} = 4.5 V	3	-3	-	ns
		V_{CC} = 6.0 V	3	-2	-	ns
C_{PD}	power dissipation capacitance	per latch; V_I = GND to V_{CC} [3]	-	42	-	pF

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +85 °C						
t_{pd}	propagation delay	nD to nQ; see Fig. 7 [1]				
		V_{CC} = 2.0 V	-	-	140	ns
		V_{CC} = 4.5 V	-	-	28	ns
		V_{CC} = 6.0 V	-	-	24	ns
		nD to n$\overline{Q}$; see Fig. 8 [1]				
		V_{CC} = 2.0 V	-	-	150	ns
		V_{CC} = 4.5 V	-	-	30	ns
		V_{CC} = 6.0 V	-	-	26	ns
		LEnn to nQ; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	-	150	ns
		V_{CC} = 4.5 V	-	-	30	ns
		V_{CC} = 6.0 V	-	-	26	ns
		LEnn to n$\overline{Q}$; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	-	155	ns
		V_{CC} = 4.5 V	-	-	31	ns
		V_{CC} = 6.0 V	-	-	26	ns
t_t	transition time	nQ, n$\overline{Q}$; see Fig. 7 and Fig. 8 [2]				
		V_{CC} = 2.0 V	-	-	95	ns
		V_{CC} = 4.5 V	-	-	19	ns
		V_{CC} = 6.0 V	-	-	16	ns
t_W	pulse width	LEnn HIGH; see Fig. 10				
		V_{CC} = 2.0 V	100	-	-	ns
		V_{CC} = 4.5 V	20	-	-	ns
		V_{CC} = 6.0 V	17	-	-	ns
t_{su}	set-up time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	75	-	-	ns
		V_{CC} = 4.5 V	15	-	-	ns
		V_{CC} = 6.0 V	13	-	-	ns
t_h	hold time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	3	-	-	ns
		V_{CC} = 4.5 V	3	-	-	ns
		V_{CC} = 6.0 V	3	-	-	ns

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
t_{pd}	propagation delay	nD to nQ; see Fig. 7 [1]				
		V_{CC} = 2.0 V	-	-	165	ns
		V_{CC} = 4.5 V	-	-	33	ns
		V_{CC} = 6.0 V	-	-	28	ns
		nD to n$\overline{Q}$; see Fig. 8 [1]				
		V_{CC} = 2.0 V	-	-	180	ns
		V_{CC} = 4.5 V	-	-	36	ns
		V_{CC} = 6.0 V	-	-	31	ns
		LEnn to nQ; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	-	180	ns
		V_{CC} = 4.5 V	-	-	36	ns
		V_{CC} = 6.0 V	-	-	31	ns
		LEnn to n$\overline{Q}$; see Fig. 10 [1]				
		V_{CC} = 2.0 V	-	-	190	ns
		V_{CC} = 4.5 V	-	-	38	ns
		V_{CC} = 6.0 V	-	-	32	ns
t_t	transition time	nQ, n$\overline{Q}$; see Fig. 7 and Fig. 8 [2]				
		V_{CC} = 2.0 V	-	-	110	ns
		V_{CC} = 4.5 V	-	-	22	ns
		V_{CC} = 6.0 V	-	-	19	ns
t_W	pulse width	LEnn HIGH; see Fig. 10				
		V_{CC} = 2.0 V	120	-	-	ns
		V_{CC} = 4.5 V	24	-	-	ns
		V_{CC} = 6.0 V	20	-	-	ns
t_{su}	set-up time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	90	-	-	ns
		V_{CC} = 4.5 V	18	-	-	ns
		V_{CC} = 6.0 V	15	-	-	ns
t_h	hold time	nD to LEnn; see Fig. 9				
		V_{CC} = 2.0 V	3	-	-	ns
		V_{CC} = 4.5 V	3	-	-	ns
		V_{CC} = 6.0 V	3	-	-	ns

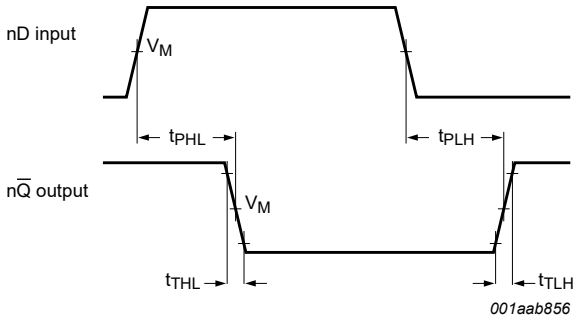
[1] t_{pd} is the same as t_{PHL} and t_{PLH}.
[2] t_t is the same as t_{THL} and t_{TLH}.
[3] C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

10.1. Waveforms and test circuit



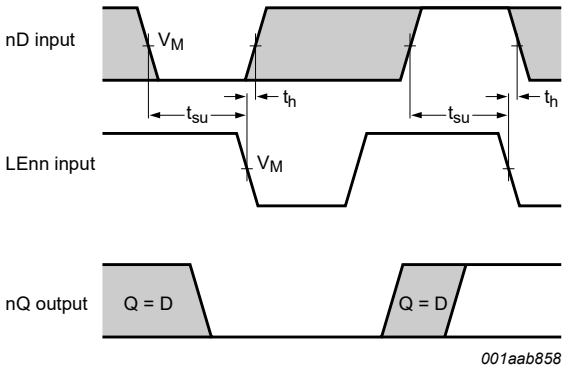
$V_M = 0.5 \times V_I$

Fig. 7. Waveforms showing the data input (nD) to output (nQ) propagation delays and the output transition times



$V_M = 0.5 \times V_I$

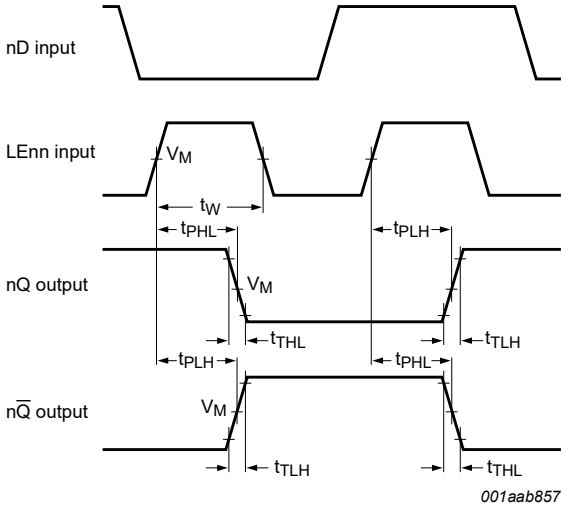
Fig. 8. Waveforms showing the data input (nD) to output (nQ̄) propagation delays and the output transition times



The shaded areas indicate when the input is permitted to change for predictable output performance.

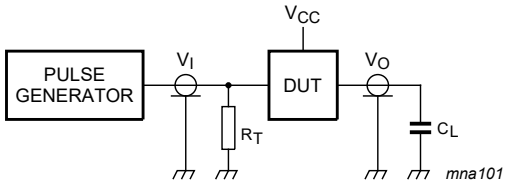
$V_M = 0.5 \times V_I$

Fig. 9. Waveforms showing the data set-up and hold times for nD input to LEnn input



$V_M = 0.5 \times V_I$

Fig. 10. Waveforms showing the latch enable input (LEnn) pulse width, the latch enable input to outputs (nQ, nQ̄) propagation delays and the output transition times



Test data is given in Table 8

Definitions for test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

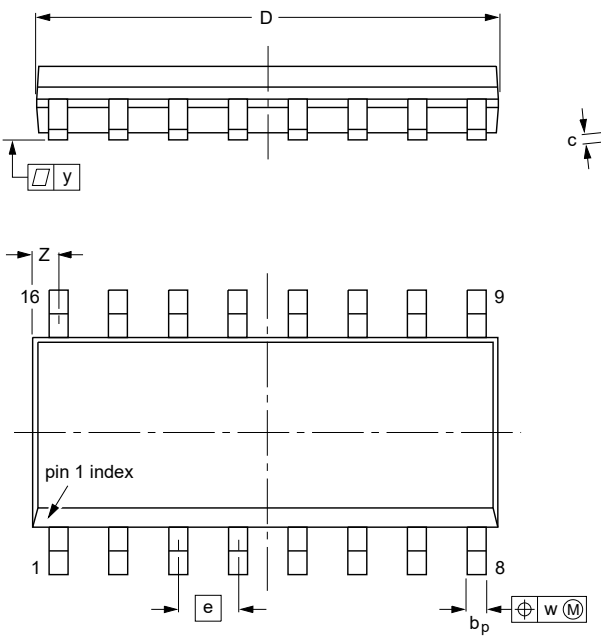
Fig. 11. Test circuit for measuring switching times

Table 8. Test data

Supply	Input		Load
V_{CC}	V_I	t_r, t_f	C_L
2.0 V	V_{CC}	6 ns	50 pF
4.5 V	V_{CC}	6 ns	50 pF
6.0 V	V_{CC}	6 ns	50 pF
5.0 V	V_{CC}	6 ns	15 pF

11. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

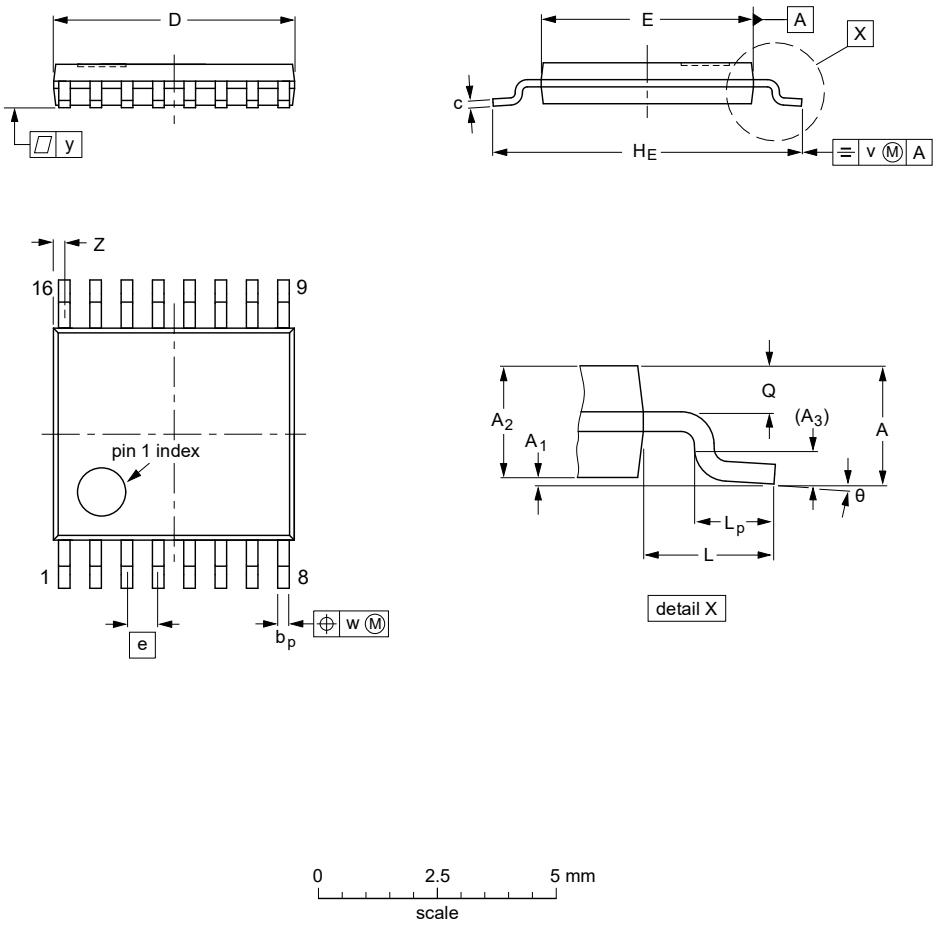
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig. 12. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig. 13. Package outline SOT403-1 (TSSOP16)

12. Abbreviations

Table 9. Abbreviations

Acronym	Abbreviation
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

13. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC75 v.5	20210317	Product data sheet	-	74HC75 v.4
Modifications:	• Section 2 updated. • Section 7: Derating values for P_{tot} total power dissipation updated. • Type number 74HC75DB (SOT338-1 / SSOP16) removed.			
74HC75 v.4	20160224	Product data sheet	-	74HC75 v.3
Modifications:	• Type number 74HC75N (SOT38-4) removed.			
74HC75 v.3	20041112	Product data sheet	-	74HC_HCT75_CNV v.2
Modifications:	• The format of this data sheet has been redesigned to comply with the current presentation and information standard of Philips Semiconductors. • Removed type number 74HCT75. • Inserted family specification.			
74HC_HCT75_CNV v.2	19970918	Product specification	-	74HC_HCT75 v.1
74HC_HCT75 v.1	19901201	Product specification	-	-

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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